

DDR3 Code Information

Module

Part Number Decoder

SAMSUNG ELECTRONICS RESERVES THE RIGHT TO CHANGE PRODUCTS, INFORMATION AND SPECIFICATIONS WITHOUT NOTICE.

Products and specifications discussed herein are for reference purposes only. All information discussed herein is provided on an "AS IS" basis, without warranties of any kind.

This document and all information discussed herein remain the sole and exclusive property of Samsung Electronics. No license of any patent, copyright, mask work, trademark or any other intellectual property right is granted by one party to the other party under this document, by implication, estoppel or otherwise.

Samsung products are not intended for use in life support, critical care, medical, safety equipment, or similar applications where product failure could result in loss of life or personal or physical harm, or any military or defense application, or any governmental procurement to which special terms or provisions may apply.

For updates or additional information about Samsung products, contact your nearest Samsung office.

All brand names, trademarks and registered trademarks belong to their respective owners.

© 2009 Samsung Electronics Co., Ltd. All rights reserved.

Part Number Decoder

M X X X **B** X X X X X X X - X X X X X
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory Module(M)

2. Module Configuration

3 : DIMM
4 : SODIMM

3~4. Data bit

71 : x64 204pin Unbuffered SODIMM
74 : x72 204pin ECC Unbuffered SODIMM
78 : x64 240pin Unbuffered DIMM
86 : x72 240pin LR DIMM
90 : x72 240pin VLP Unbuffered DIMM
91 : x72 240pin ECC Unbuffered DIMM
92 : x72 240pin VLP Registered DIMM

5. DRAM Component Type

B : DDR3 SDRAM(1.5V VDD)

6~7. Depth

32 : 32M	33 : 32M (for 128Mb / 512Mb)
64 : 64M	65 : 64M (for 128Mb / 512Mb)
28 : 128M	29 : 128M (for 128Mb / 512Mb)
56 : 256M	57 : 256M (for 512Mb / 2Gb)
51 : 512M	52 : 512M (for 512Mb / 2Gb)
1G : 1G	1K : 1G (for 2Gb)
2G : 2G	2K : 2G (for 2Gb)
4G : 4G	

8. # of bank in Comp., Interface

7 : 8bank, SSTL(1.5V)

9. Bit Organization

0 : x4 3 : x8
4 : x16

10. Component Revision

M : M-die	A : A-die
B : B-die	C : C-die
D : D-die	E : E-die
F : F-die	G : G-die

11. Package

Z : FBGA (Lead-Free)
H : FBGA (Lead-Free & Halogen-Free)
J : FBGA (Lead-Free, DDP)
M : FBGA (Lead-Free & Halogen-Free, DDP)
B : FBGA (Lead-Free & Halogen-Free, Flip Chip)
E : FBGA (Lead-Free & Halogen-Free, QDP)

12. PCB Revision

0 : None	1 : 1st Rev.
2 : 2nd Rev.	3 : 3rd Rev.
4 : 4th Rev.	

13. "-"

14. Temp & Power

C : Commercial Temp (0°C ~ 85°C), Normal Power
Y : Commercial Temp (0°C ~ 85°C), Low VDD (1.35V)

15~16. Speed

F7 : DDR3-800 (400MHz@CL=6, tRCD=6, tRP=6)
F8 : DDR3-1066 (533MHz@CL=7, tRCD=7, tRP=7)
H9 : DDR3-1333 (667MHz@CL=9, tRCD=9, tRP=9)
K0 : DDR3-1600 (800MHz@CL=11, tRCD=11, tRP=11)
MA : DDR3-1866 (933MHz@CL=13, tRCD=13, tRP=13)

17. Memory Buffer

0 : Inphi iMB02-GS02A
1 : IDT MB3 B0
8 : IDT AI (evergreen)
9 : Inphi UVGS02